

ABSTRACT

Sub A2

A method for the removal of voids and gas bubbles within uncured or partially cured microelectronic component encapsulants and adhesive/chip attach layers. A sealed void or gas bubble within a gap between a microelectronic component and a supporting substrate is substantially eliminated through the application of a uniform pressure (isostatic or hydrostatic) and energy such that a substantially void/bubble free interposer layer is created.

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